MA2SD32

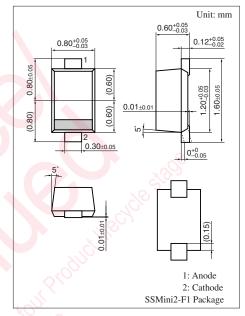
Silicon epitaxial planar type

For super high speed switching

Features

- $I_{F(AV)} = 200$ mA rectification is possible.
- Small reverse current: $I_R < 5 \ \mu A$ (at $V_R = 30 \ V$)

Absolute Maximum Ratings $T_a = 25^{\circ}C$								
Parameter	Symbol	Rating	Unit					
Reverse voltage	V _R	30	v					
Repetitive peak reverse voltage	V _{RRM}	30	V					
Forward current (Average)	I _{F(AV)}	200	mA					
Peak forward current	I _{FM}	300	mA					
Non-repetitive peak forward surge current *	I _{FSM}	1	А					
Junction temperature	Tj	125	°C					
Storage temperature	T _{stg}	-55 to +125	°C					



Marking Symbol: 8H

Note) * : The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

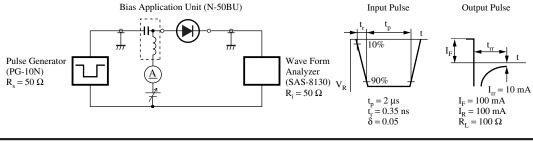
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Reverse current		I _{R1}	$V_R = 10 V$		9% ⁻	0.5	μΑ
		I _{R2}	$V_{R} = 30 V$	00	SOL	5	
Forward voltage		V _F	$I_{\rm F} = 200 \text{ mA}$		0.49	0.56	V
Terminal capacitance	~	C _t	$V_R = 0 V, f = 1 MHz$, 90	25		pF
Reverse recovery time *		t _{rr}	$I_F = I_R = 100 \text{ mA}$		2		ns
			$I_{\rm rr} = 10 \text{ mA}, R_{\rm L} = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

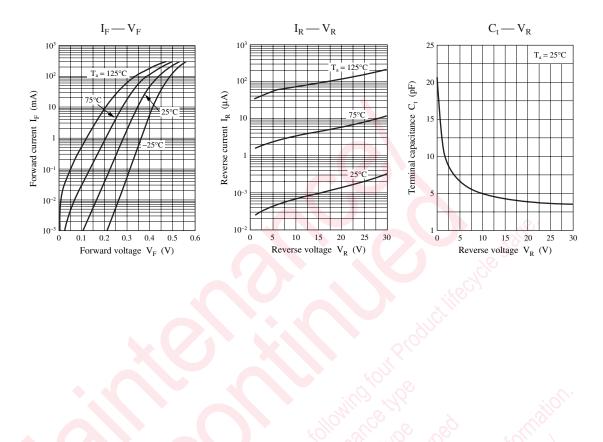
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 250 MHz
- 4. *: t_{rr} measurement circuit



MA2SD32





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